

## **What is claimed is:**

**[Claim 1]** 1. A method of making an RFID device which includes the steps of:

(a) applying a UV curable adhesive having electrically conductive particles therein to a pair of laterally displaced landing sites of an antenna formed on a UV penetrable web in a manner such that said particles remain spatially positioned from one another,

(b) bringing a pair die pads of a die into sufficient electrical contact with said landing sites to effect a Z axis conductivity through the particles between a respective die pad and landing site pad pair while precluding X-Y conductivity between the landing site pads, and

(c) UV irradiating of the adhesive in a manner to cure said adhesive joining said die to said antenna.

**[Claim 2]** 2. The method of claim 1, which further characterizes the step (a) wherein said particles are metallic coated spheres.

**[Claim 3]** 3. The method of claim 1, which further characterizes the step (c) to include introducing an inert gas into an area surrounding an exposed portion of said adhesive.

**[Claim 4]** 4. The method of claim 1, which further characterizes the step (c) to include irradiating through the web.

**[Claim 5]** 5. An RFID device made in accordance with the method of claim 1.

**[Claim 6]** 6. An RFID device, which includes:

a UV penetrable substrate;

an antenna adhered to said substrate having a landing site extending therefrom;

a die chip having a die pad extending therefrom which is disposed adjacent said antenna; and

a UV cured adhesive having electrically conductive particles dispersed therethrough in a manner to only provide electrical conductivity between said landing site and said die pad, and wherein said adhesive bonds said die chip and said antenna.